

**TIF™100-40-11US Series** thermally conductive interface materials are applied to fill the air gaps between the heating elements and the heat dissipation fins or the metal base. Their flexibility and elasticity make them suited to coat very uneven surfaces. Heat can transmit to the metal housing or dissipation plate from the heating elements or even the entire PCB, which effectively enhances the efficiency and life-time of the heat-generating electronic components.

**Features**

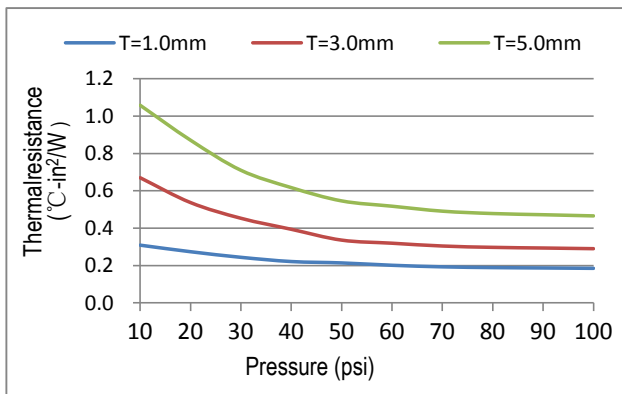
- » Good thermal conductivity: **4.0 W/mK**
- » Naturally tacky needing no further adhesive coating
- » Soft and Compressible for low stress applications
- » Available in varies thickness

**Application**

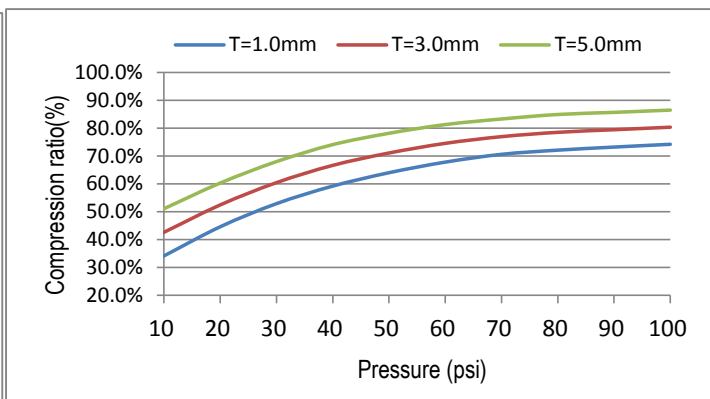
- » Cooling components to the chassis of frame
- » Set Top Box
- » Car Battery & Power Supply
- » Charging Pile
- » LED TV/ Lighting
- » Graphics Card Thermal Module

| Typical Properties of TIF™100-40-11US Series |                                   |            |
|----------------------------------------------|-----------------------------------|------------|
| Color                                        | Gray                              | Visual     |
| Construction                                 | Ceramic filled silicone elastomer | *****      |
| Thickness range                              | 0.020"(0.5mm)~0.200" (5.0mm)      | ASTM D374  |
| Hardness                                     | 20 Shore 00                       | ASTM 2240  |
| Density ( (g/cm³) )                          | 3.15                              | ASTM D297  |
| Operating Temp                               | -40 ~160 °C                       | *****      |
| Dielectric Breakdown Voltage                 | >5500 VAC                         | ASTM D149  |
| Dielectric Constant@1MHz                     | 4.0 MHz                           | ASTM D150  |
| Volume Resistivity                           | >6.0X10 <sup>12</sup> Ohm-cm      | ASTM D257  |
|                                              | 4.0 W/mK                          | ASTM D5470 |
| Thermal Conductivity                         | 4.0 W/mK                          | GB-T32064  |
|                                              | 94 -V0                            | UL E331100 |

**Pressure. vs. Thermal impedance**



**Pressure. vs. Compression Ratio**



**Product Specification**

**Product Thicknesses:** 0.020-inch to 0.200-inch (0.5mm to 5.0mm)

**Product Sizes:** 8" x 16"(203mm x406mm)

Individual die cut shapes and custom thickness can be supplied. Please contact us for

Application Technology Download  
Thermal Conductive Interface Materials



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